

Standardize the requirements for through-hole reflow mounting PG

◆ Purpose / Scope

- We aim to standard the requirements for the through-hole reflow mounting(THR), as for terms, parts, materials, printed wiring boards and processes.
- Regarding to the above, we aim to establish the JEITA standards and revise the IEC standards.

◆ Overview of activities

- Reflow soldering is a method to solder surface mounting parts on printed wiring board and it is becoming the main method to mount electrical and electronic components. But some parts which cannot be surface mounted like high power components are still handled by hand soldering, laser soldering, partial soldering. These methods are done separately with reflow soldering and need man-hour and equipment. So, through-hole reflow mounting which soldering lead of mounting parts in the process of surface mounting is increasingly adopted.
- But requirements for through-hole reflow mounting are different in various parts and companies so standardization of requirements are necessary. In order to standardize requirement for through-hole reflow mounting, project consisted by consisted by set maker, component maker, material maker, equipment maker is made since March 2017.
- Through past years' activity, ET-7505 became JEITA standard. ET-7505 also is considered to be IEC standard for replacement of IEC 61760-3.

◆ Standards in charge

IEC standards	JIS Correspondence	JEITA standards	Name
IEC 61760-3 Ed.1	Not support	Not support	Standard method for the specification of components for through hole reflow (THR) soldering
Proposing revision of IEC 61760-3 Ed.3	Not support	ET-7505	Requirements for through hole (THR) soldering